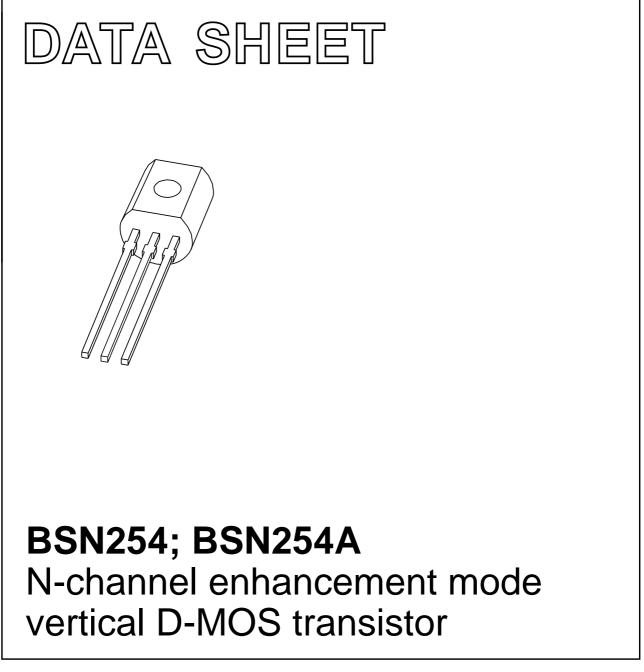
## DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 1997 Jun 23 2002 Feb 19



### **BSN254; BSN254A**

### FEATURES

- Direct interface to C-MOS, TTL, etc.
- High-speed switching
- No secondary breakdown
- Low R<sub>DSon</sub>.

### APPLICATIONS

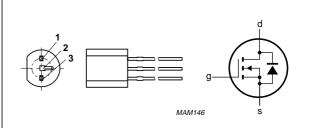
- Line current interruptor in telephone sets
- Relay, high-speed and line transformer drivers.

### DESCRIPTION

N-channel enhancement mode vertical D-MOS transistor in a SOT54 (TO-92) variant package.

### PINNING - SOT54 variant

PIN	DESCRIPTION		
FIN	BSN254	BSN254A	
1	gate	source	
2	drain	gate	
3	source	drain	



note: various pinnings are available on request

Fig.1 Simplified outline and symbol.

### QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V <sub>DS</sub>	drain-source voltage (DC)		_	250	V
I <sub>D</sub>	drain current (DC)		_	310	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	-	1	W
R <sub>DSon</sub>	drain-source on-state resistance	$I_D = 300 \text{ mA}; V_{GS} = 10 \text{ V}$	2.8	5	Ω
V <sub>GSth</sub>	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$	_	2	V

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>DS</sub>	drain-source voltage (DC)		-	250	V
V <sub>GSO</sub>	gate-source voltage (DC)	open drain	-	±20	V
I <sub>D</sub>	drain current (DC)		_	310	mA
I <sub>DM</sub>	peak drain current		-	1.25	А
P <sub>tot</sub>	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C;$ note 1	-	1	W
T <sub>stg</sub>	storage temperature		-55	+150	°C
Tj	junction temperature		-	150	°C

#### Note

1. Device mounted on a printed-circuit board; maximum lead length 4 mm; mounting pad for drain lead minimum  $10 \times 10$  mm.

### BSN254; BSN254A

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient; note 1	125	K/W

#### Note

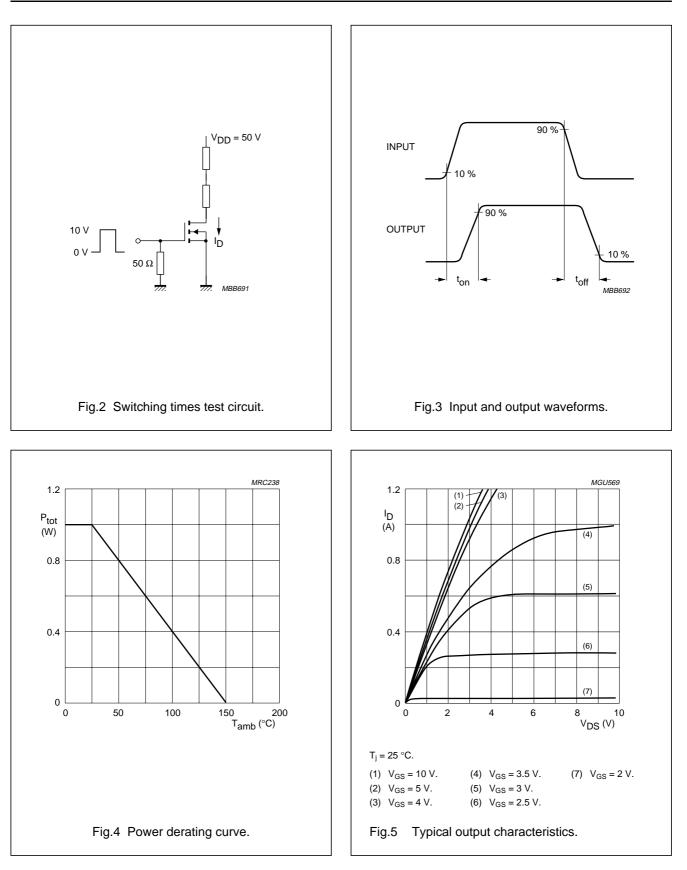
1. Device mounted on a printed-circuit board; maximum lead length 4 mm; mounting pad for drain lead minimum  $10 \times 10$  mm.

### **CHARACTERISTICS**

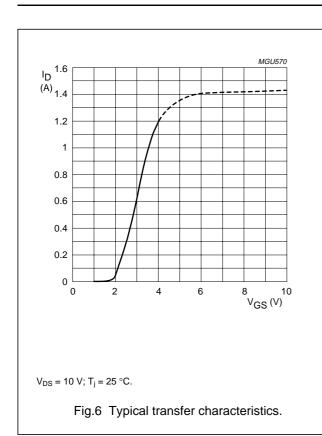
 $T_i = 25 \ ^{\circ}C$  unless otherwise specified.

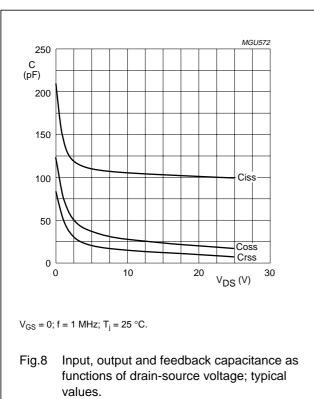
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	$I_D = 10 \ \mu A; \ V_{GS} = 0$	250	_	-	V
I <sub>GSS</sub>	gate-source leakage current	$V_{GS} = \pm 20 \text{ V}; V_{DS} = 0$	-	-	±100	nA
V <sub>GSth</sub>	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$	0.8	-	2	V
R <sub>DSon</sub>	drain-source on-state resistance	$I_D = 20 \text{ mA}; V_{GS} = 2.4 \text{ V}$	-	-	7.5	Ω
		I <sub>D</sub> = 300 mA; V <sub>GS</sub> = 10 V	-	2.8	5	Ω
I <sub>DSS</sub>	drain-source leakage current	$V_{DS} = 200 \text{ V}; V_{GS} = 0$	-	-	1	μA
Y <sub>fs</sub>	transfer admittance	$I_D = 300 \text{ mA}; V_{DS} = 25 \text{ V}$	200	600	-	mS
C <sub>iss</sub>	input capacitance	$V_{DS} = 25 \text{ V}; V_{GS} = 0; \text{ f} = 1 \text{ MHz}$	-	100	120	pF
C <sub>oss</sub>	output capacitance	V <sub>DS</sub> = 25 V; V <sub>GS</sub> = 0; f = 1 MHz	-	21	30	pF
C <sub>rss</sub>	feedback capacitance	$V_{DS} = 25 \text{ V}; V_{GS} = 0; f = 1 \text{ MHz}$	_	10	15	pF
Switching tir	nes (see Figs 2 and 3)					
t <sub>on</sub>	turn-on time	$I_D = 250 \text{ mA}; V_{DD} = 50 \text{ V};$ $V_{GS} = 0 \text{ to } 10 \text{ V}$	-	6	10	ns
t <sub>off</sub>	turn-off time	$I_D = 250 \text{ mA}; V_{DD} = 50 \text{ V};$ $V_{GS} = 10 \text{ to } 0 \text{ V}$	-	47	60	ns

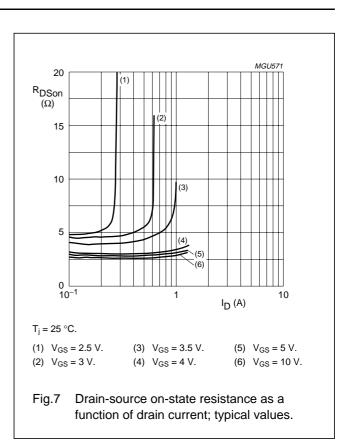
### BSN254; BSN254A



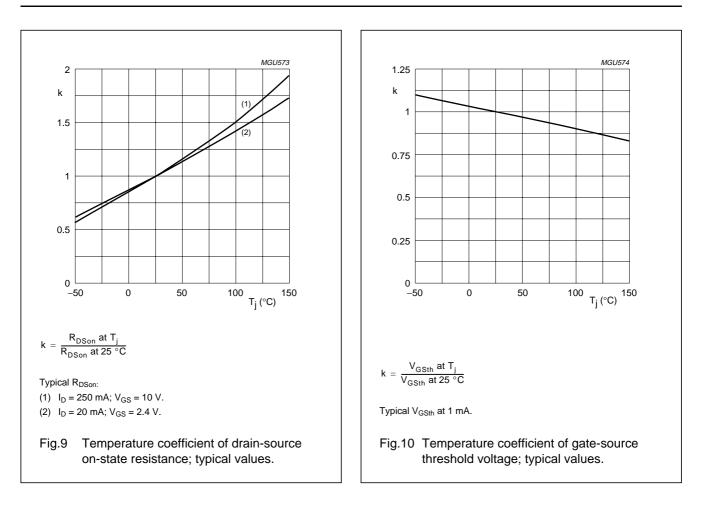
## BSN254; BSN254A







## BSN254; BSN254A

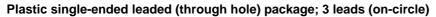


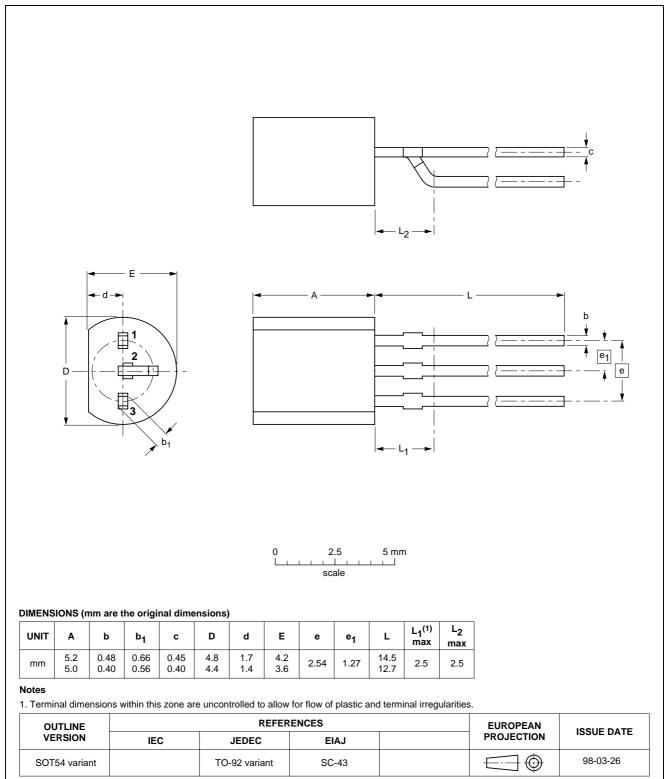
SOT54 variant

# N-channel enhancement mode vertical D-MOS transistor

### BSN254; BSN254A

### PACKAGE OUTLINE





### BSN254; BSN254A

### DATA SHEET STATUS

DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A.

#### Notes

- 1. Please consult the most recently issued data sheet before initiating or completing a design.
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# BSN254; BSN254A

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# BSN254; BSN254A

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